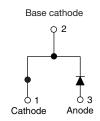


Hyperfast Rectifier, 30 A FRED Pt®





PRIMARY CHARACTERISTICS						
I _{F(AV)}	30 A					
V_{R}	600 V					
V _F at I _F	1.4 V					
t _{rr} typ.	26 ns					
T _J max.	175 °C					
Package	TO-247AD 2L					
Circuit configuration	Single					

FEATURES

- Low forward voltage drop
- · Hyperfast soft recovery time
- 175 °C operating junction temperature
- Designed and qualified according to commercial qualification





ROHS COMPLIANT HALOGEN

FREE

DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V _{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 112 °C	30	^			
Non-repetitive peak surge current	I _{FSM}	$T_C = 25$ °C, $t_p = 8.3$ ms half sine wave	240	A			
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-			
Forward voltage	V _F	I _F = 30 A	-	2.0	2.65	V		
		I _F = 30 A, T _J = 150 °C	-	1.4	1.8			
Poverse leekage current	1	V _R = V _R rated	-	0.02	30			
Reverse leakage current	I _R	T _J = 150 °C, V _R = V _R rated	-	-	300	μΑ		
Junction capacitance	C _T	V _R = 600 V	-	20	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH		



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	26	-		
Reverse recovery time	t _{rr}	T _J = 25 °C	$I_F = 30 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	26	-	ns	
		T _J = 125 °C		-	70	-		
Dook receivent current	I _{RRM}	T _J = 25 °C		-	3.5	-	Α	
Peak recovery current		T _J = 125 °C		-	7.6	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	50	-	nC	
		T _J = 125 °C		-	280	-		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C	
Thermal resistance, junction to case	R _{thJC}		-	0.7	1.1	°C/W	
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-		
Mojekt			-	5.5	-	g	
Weight			-	0.2	-	oz.	
Mounting torque			1.2 (10)	-	2.4 (20)	kgf · cm (lbf · in)	
Marking device		Case style TO-247AD 2L		EPH	3006L		

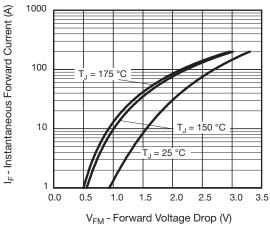


Fig. 1 - Typical Forward Voltage Drop Characteristics

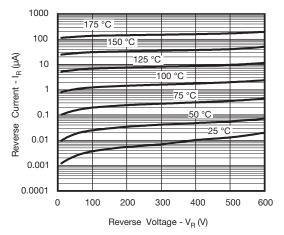


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

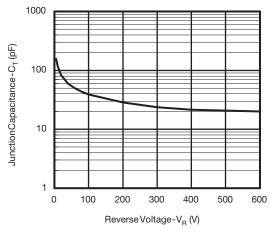


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

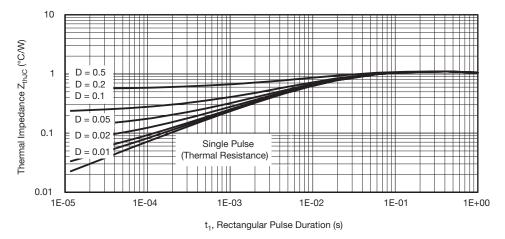


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

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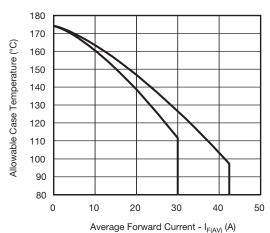


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

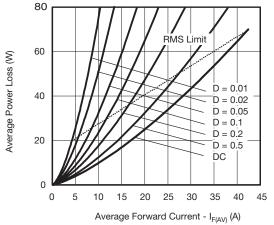


Fig. 6 - Forward Power Loss Characteristics

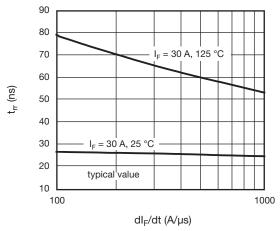


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

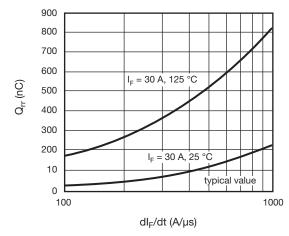
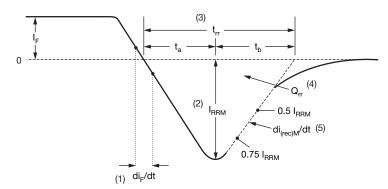


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\rm Q_{rr}$ area under curve defined by $\rm t_{rr}$ and $\rm I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

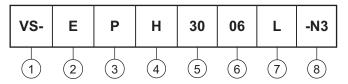
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

- • A = single diode

• E = single diode

3 - P = TO-247

4 - H = hyperfast recovery time

- Current code (30 = 30 A)

6 - Voltage code (06 = 600 V)

7 - L = long lead

8 - Environmental digit:

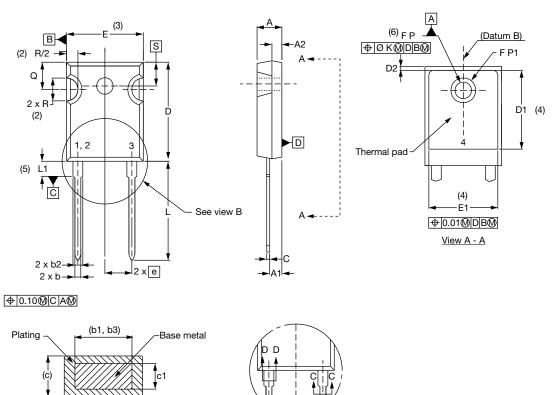
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-EPH3006L-N3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-247AD 2L	www.vishay.com/doc?95536			
Part marking information	TO-247AD 2L	www.vishay.com/doc?95648			
SPICE model		www.vishay.com/doc?96580			

TO-247AD 2L

DIMENSIONS in millimeters and inches



View B

SYMBOL	MILLIN	MILLIMETERS		INCHES	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4
D2	0.51	1.35	0.020	0.053	

Section C - C, D - D

SYMBOL	MILLIN	IETERS	INC	INCHES		
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Е	15.29	15.87	0.602	0.625	3	
E1	13.46	-	0.53	-		
е	5.46	BSC	0.215	BSC		
ØK	0.254		0.0	0.010		
L	19.81	20.32	0.780	0.800		
L1	3.71	4.29	0.146	0.169		
ØΡ	3.56	3.66	0.14	0.144		
Ø P1	-	6.98	-	0.275		
Q	5.31	5.69	0.209	0.224		
R	4.52	5.49	0.178	0.216		
S	5.51 BSC		0.217 BSC			
	•		•	•		

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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